Satisfy the performance demands of your low power embedded applications with the AMD Embedded G-Series platform. The world’s first embedded APU with a brand new low power x86 CPU core and advanced discrete class GPU in a single chip. These APUs offer outstanding performance and energy efficiency without compromising performance or compatibility.

### Outstanding Overall Performance

<table>
<thead>
<tr>
<th>Processor</th>
<th>Score</th>
</tr>
</thead>
<tbody>
<tr>
<td>AMD G-Series T56N</td>
<td>111%</td>
</tr>
<tr>
<td>AMD G-Series T48N</td>
<td>107%</td>
</tr>
<tr>
<td>Intel Atom D525/Gen2 nVidia ION</td>
<td>100%</td>
</tr>
<tr>
<td>AMD G-Series T40N</td>
<td>76%</td>
</tr>
<tr>
<td>Intel Atom D525</td>
<td>48%</td>
</tr>
</tbody>
</table>

Performance benchmarks are the geometric mean of compiled data from the list of overall benchmark scores from the listed tests. The geometric mean of scores is normalized to the Intel Atom D525 processor with nVidia Generation 2 ION discrete graphics. Performance benchmark system configurations on next page.

### Features and Benefits

- Integration of APU reduces footprint, simplifies design, requiring fewer board layers, and a smaller power supply, further driving down system costs.

- The AMD G-Series platform delivers a 32% smaller footprint than the Atom D525+ION2, a 38% smaller footprint than the Intel Atom 400 and 500 series and a 12% smaller footprint than the Intel Atom E6xx series.¹

- Advanced graphics processing with support for DirectX® 11 technology, OpenGL 4.0 and OpenCL™ in an integrated device provides the foundation to build the designs of tomorrow, today.

- AMD Virtualization™ technology helps virtualization software run securely and efficiently.

- Ideal for low power designs such as Digital Signage, Integrated Set-Top-Box (xSTB), IP-TV, Thin Client, Information Kiosk, Point-of-Service, and Casino Gaming markets.

¹ 890 mm² vs. 1302 mm², 1445 mm² and 1013 mm² respectively.
System Configurations

Operating System
Name: Windows® XP Professional
Version: Service Pack 2
Build: 2600
DirectX® Version: DirectX® 9.0C

Processor
Name: AMD Embedded G-Series
Version: T56N
Build: AMD Embedded G-Series T56N

Hardware
Motherboard: iBase Mi955
BIOS Info: 0ABVQ 0.11 x64
North Bridge: Integrated on AMD Embedded G-Series
South Bridge: AMD A55E Controller Hub
Memory
Manufacturer and Type: Crucial CT25664BA1339.M8FD
Quantity & Size each: Qty (1) 2 GB SODIMM
Total Memory Size: 2GB
Hard Drive: Hitachi HTS725016A9A364
Drive Size: 160GB
Transfer Mode: SATA 3.0Gbps, NTFS

Network Card
Model Number: Integrated Realtek 10/100/1000
Video Card
Graphics Adapter: Integrated on AMD Embedded G-Series
Processor: 512MB, UMA
Network Driver
Model Number: Integrated Intel 10/100/1000
Audio Driver
Model Number: nVidia Gen2 ION
Video Driver
Model Number: rVidia Gen2 ION
CPU Driver
Model Number: Integrated Intel 10/100/1000
Other
-Memory timings were unknown
-Actual memory speed was 533MHz
-(DDR3-1066)

Performance Benchmark Suite
- Futuremark 3DMark™06 v1.2.0
- POV Ray 3.7 Beta 23
- BAPCO® SYSmark® 2007 Preview Rating, v1.05.958

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